

# KENWOOD

ASB-

1055

## Service Bulletin

Amateur Radio Division

**Subject:** Power Module Heat Sink Compound  
2006

**Date:** December 5,

### Symptom:

Several current and past model transceivers do not use Heat Sink Compound on the power modules. Our engineering department determined through testing, that those models with fine castings or machined areas under the power module do not really require its use. Several service facilities and customers have questioned this and are concerned that this could eventually cause failure of the power module(s).

### Corrective Action:

In order to ease any concerns and to increase your confidence our engineers recommend that you use Silicone Heat Compound whenever replacing any of these devices or whenever they must be lifted for service of other components on the board. Our production lines will begin using this compound again as added protection for these devices.

### Parts Required:

Qty	Description	New Part No.	Circuit Description
1	Silicone Heat Sink Compound	W01-0411-05	NA

